## **KB DDLM31.13**

### SYNIOS® S2222

This square package with just 2mm outline combines best performance with a small footprint. A centralized chip allows an easy integration in optical systems. The availability of different main colors and white points gives highest flexibility in various application areas.











### **Applications**

- Architecture / Garden Lighting (LED & Laser)
- Electronic Equipment
- Industrial Automation (Machine Controls, Light Barriers, Vision Controls)
- Mood Lighting
- Smart Home, Metering
- Transportation, Plane, Ship
- White Goods

### Features:

- Package: white SMT package, colorless clear silicone resin
- Chip technology: InGaN on Sapphire
- Typ. Radiation: 120° (Lambertian emitter)
- − Color:  $\lambda_{dom}$  = 450 nm (• blue)
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)



Ordering Information		
Туре	Luminous Flux <sup>1)</sup> $I_F = 140 \text{ mA}$ $\Phi_V$	Ordering Code
KB DDLM31.13-6D7E-25-24A4	5000 10000 mlm	Q65112A5716



### **KB DDLM31.13**

Maximum Ratings			
Parameter	Symbol		Values
Operating Temperature	T <sub>op</sub>	min. max.	-40 °C 110 °C
Storage Temperature	$T_{stg}$	min. max.	-40 °C 110 °C
Junction Temperature	T <sub>j</sub>	max.	125 °C
Forward current T <sub>S</sub> = 25 °C	I <sub>F</sub>	min. max.	10 mA 200 mA
Surge Current t $\leq$ 10 $\mu$ s; D = 0.005 ; T <sub>s</sub> = 25 °C	I <sub>FS</sub>	max.	400 mA
Reverse voltage <sup>2)</sup> T <sub>S</sub> = 25 °C	$V_R$	max.	5 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	$V_{ESD}$		2 kV



## **Characteristics**

 $I_F$  = 140 mA;  $T_S$  = 25 °C

Parameter	Symbol		Values
Dominant Wavelength <sup>3)</sup> I <sub>F</sub> = 140 mA	$\lambda_{\sf dom}$	min. typ. max.	444 nm 450 nm 461 nm
Viewing angle at 50% I <sub>v</sub>	2φ	typ.	120 °
Forward Voltage <sup>4)</sup> I <sub>F</sub> = 140 mA	$V_{F}$	min. typ. max.	2.80 V 3.15 V 3.40 V
Reverse current <sup>2)</sup> V <sub>R</sub> = 5 V	I <sub>R</sub>	typ. max.	0.01 μA 10 μA
Real thermal resistance junction/solderpoint 5)	$R_{ ext{thJS real}}$	typ. max.	31 K / W 40 K / W
Electrical thermal resistance junction/solderpoint $^{5)}$ with efficiency $\eta_e$ = 55 %	$R_{ ext{thJS elec.}}$	typ. max.	14 K / W 18 K / W



# **Brightness Groups**

Group	Luminous Flux <sup>1)</sup> I <sub>F</sub> = 140 mA min.	Luminous Flux <sup>1)</sup> I <sub>F</sub> = 140 mA	Luminous Intensity <sup>6)</sup> I <sub>F</sub> = 140 mA	
	Φ <sub>V</sub>	max. Φ <sub>v</sub>	typ. I <sub>v</sub>	
6D	5000 mlm	5600 mlm	1750 mcd	_
7D	5600 mlm	6300 mlm	1960 mcd	
8D	6300 mlm	7100 mlm	2210 mcd	
5E	7100 mlm	8000 mlm	2490 mcd	
6E	8000 mlm	9000 mlm	2810 mcd	
7E	9000 mlm	10000 mlm	3140 mcd	

# **Forward Voltage Groups**

Group Forward Voltage $^{4)}$ $I_{F}$ = 140 mA min. $V_{F}$		Forward Voltage 4)  I <sub>F</sub> = 140 mA  max.  V <sub>F</sub>	
24	2.80 V	3.00 V	
64	3.00 V	3.20 V	
A4	3.20 V	3.40 V	

# **Wavelength Groups**

Group	Dominant Wavelength <sup>3)</sup> I <sub>F</sub> = 140 mA min.	Dominant Wavelength <sup>3)</sup> I <sub>F</sub> = 140 mA max.
	$\lambda_{\sf dom}$	$\lambda_{dom}$
2	444 nm	449 nm
3	449 nm	453 nm
4	453 nm	457 nm
5	457 nm	461 nm



## **Group Name on Label**

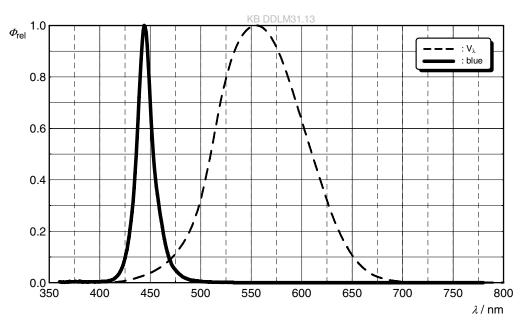
Example: 5E-2-24

Brightness	Wavelength	Forward Voltage
5E	2	24



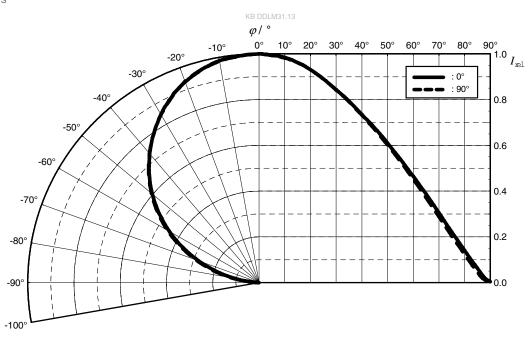
## Relative Spectral Emission 6)

$$\Phi_{rel}$$
 = f ( $\lambda$ ); I $_F$  = 140 mA; T $_S$  = 25 °C



# Radiation Characteristics 6)

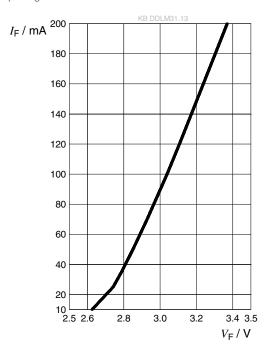
$$I_{rel} = f(\phi); T_S = 25 °C$$





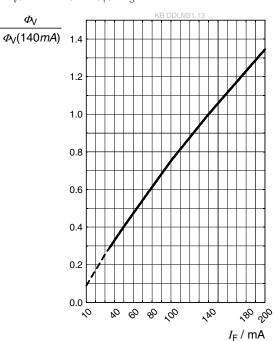
## Forward current 6)

$$I_F = f(V_F); T_S = 25 \, ^{\circ}C$$



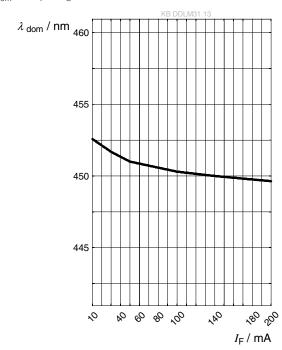
## Relative Luminous Flux 6), 7)

$$\Phi_v / \Phi_v (140 \text{ mA}) = f(I_F); T_S = 25 \text{ }^{\circ}\text{C}$$



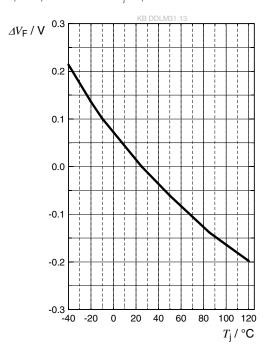
## **Dominant Wavelength** 6)

$$\lambda_{dom} = f(I_F); T_S = 25 \text{ }^{\circ}\text{C}$$



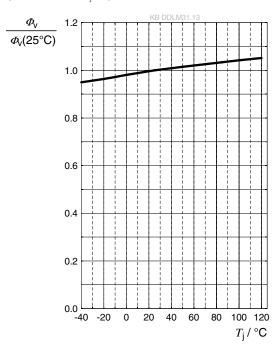
## Forward Voltage 6)

$$\Delta V_{_F} = V_{_F} - V_{_F} (25 \ ^{\circ}C) = f(T_{_j}); \ I_{_F} = 140 \ mA$$



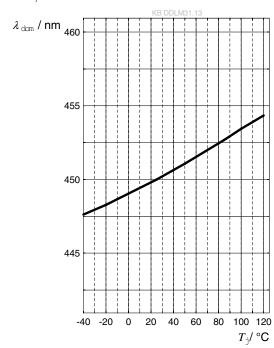
## Relative Luminous Flux 6)

$$\Phi_{v}/\Phi_{v}(25~^{\circ}\text{C}) = f(T_{i}); I_{F} = 140~\text{mA}$$



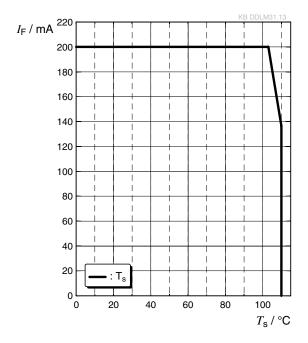
## **Dominant Wavelength** 6)

$$\lambda_{dom} = f(T_j); I_F = 140 \text{ mA}$$



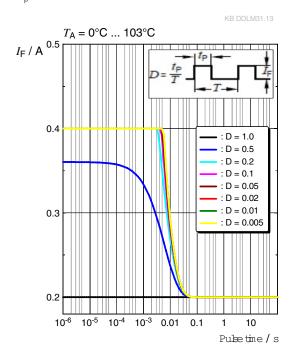
## Max. Permissible Forward Current

 $I_{\scriptscriptstyle F} = f(T)$ 



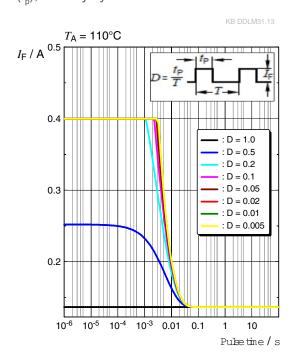
## **Permissible Pulse Handling Capability**

 $I_F = f(t_p)$ ; D: Duty cycle



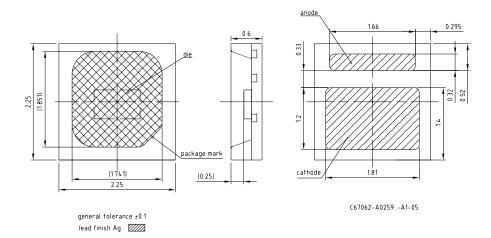
## **Permissible Pulse Handling Capability**

 $I_F = f(t_p)$ ; D: Duty cycle





# Dimensional Drawing 8)

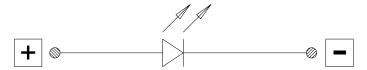


## **Further Information:**

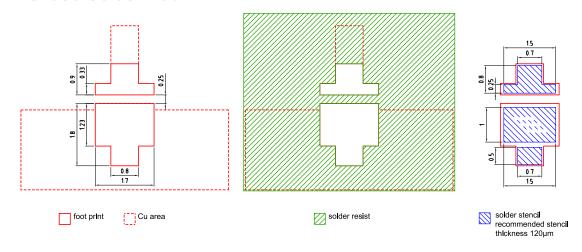
**Approximate Weight:** 6.0 mg

Package marking: Cathode

## **Electrical Internal Circuit**



## Recommended Solder Pad 8)



board material selection has high impact on system reliability

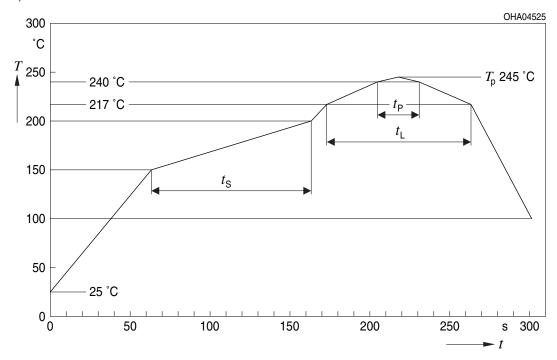
E062.3010.249 -01

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



## **Reflow Soldering Profile**

Product complies to MSL Level 3 acc. to JEDEC J-STD-020E



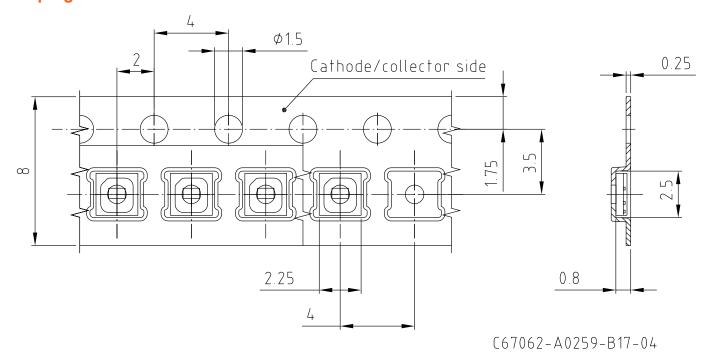
Profile Feature Symbol Pb-Free (SnAgCu) Assembly			sembly	Unit	
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*)			2	3	K/s
25 °C to 150 °C					
Time t <sub>s</sub>	$t_s$	60	100	120	S
$T_{Smin}$ to $T_{Smax}$					
Ramp-up rate to peak*)			2	3	K/s
$T_{Smax}$ to $T_{P}$					
Liquidus temperature	$T_L$		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle \perp}$		80	100	S
Peak temperature	$T_{P}$		245	260	°C
Time within 5 °C of the specified peak	t <sub>P</sub>	10	20	30	S
temperature T <sub>P</sub> - 5 K					
Ramp-down rate*			3	6	K/s
T <sub>P</sub> to 100 °C					
Time				480	S
25 °C to T <sub>P</sub>					

All temperatures refer to the center of the package, measured on the top of the component

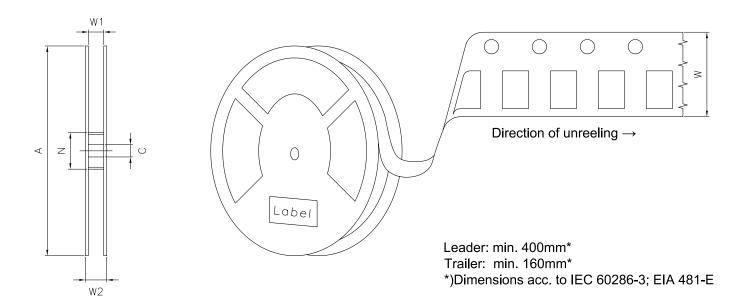


<sup>\*</sup> slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

# Taping 8)



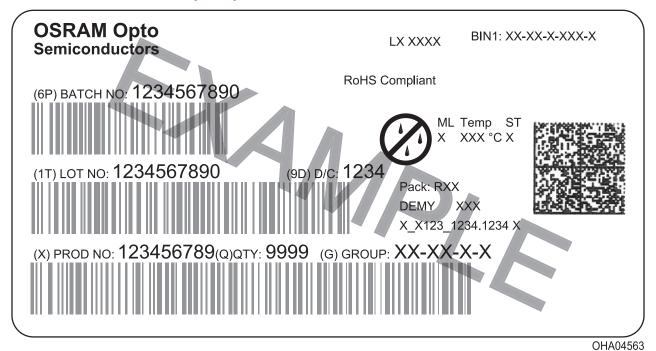
## Tape and Reel 9)



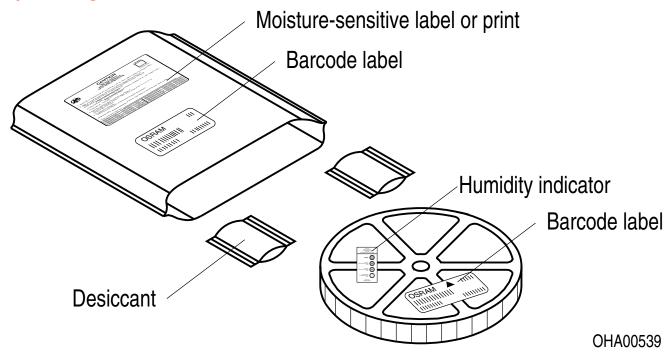
## **Reel Dimensions**

Α	W	$N_{\min}$	$W_1$	$W_{2 \text{ max}}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1 mm	60 mm	8.4 + 2 mm	14.4 mm	4000

### **Barcode-Product-Label (BPL)**



## Dry Packing Process and Materials 8)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



#### **Notes**

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **moderate risk (exposure time 0.25 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



#### **Disclaimer**

#### Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

#### **Packing**

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

### Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.



### Glossary

- Brightness: Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of k = 3).
- Reverse Operation: This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- Wavelength: The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k =
- Forward Voltage: The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).
- 5) **Thermal Resistance:** Rth max is based on statistic values (6σ).
- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



### **KB DDLM31.13**

Revision History			
Version	Date	Change	
1.0	2019-12-15	Initial Version	
1.1	2020-01-13	Brand	
1.2	2020-04-24	Schematic Transportation Box Dimensions of Transportation Box	
1.3	2020-07-17	Product Image	



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